# **Alex Mazursky**

Product Design Engineer at Apple a\_mazursky@apple.com | www.alexmazursky.com

# **ABOUT ME**

I engineer new technology, from circuits to mechanisms to applications. I love learning and building fast.

My PhD research focused on **designing wearable devices that provide haptic feedback** (touch sensations), transforming otherwise passive objects and surfaces into interactive experiences. I specialize in **engineering actuators from the ground up**, and integrating actuators into **custom devices** that create diverse sensations—such as vibration, friction, pressure, and temperature—to **augment physical & virtual spaces (AR/VR)**. In addition to haptics, my research has explored digital fabrication (tools for 3D printing & silicone casting) & human-robot interaction.

My multidisciplinary background in **mechanical engineering & computer science** supports designing and implementing systems from the **fundamental mechanics to the end application**. I have been privileged to pursue these projects at places like **Apple, Meta, University of Chicago, & KAIST**.

### **EDUCATION**

<b>University of Chicago</b> PhD (& MS) in Computer Science Advisor: Prof. Pedro Lopes, Human Computer Integration Lab	2019 – 2025
<b>Miami University</b> MS in Mechanical Engineering Advisor: Prof. Jeong-Hoi Koo, Smart Materials Lab Supported by a <b>Graduate Fellowship from NASA</b> (Ohio Space Grant Consortium)	2019
<b>Miami University</b> BS in Mechanical Engineering, Energy Co-Major Summa Cum Laude, Departmental and University Honors	<b>2018</b> GPA: 3.92/4.00
EXPERIENCE	
Apple, Haptic Hardware Engineering Product Design Engineer ▷ Engineering next-generation haptic actuators for Apple products	Mar 2025 – Present San Diego, CA
University of Chicago, Department of Computer Science	Aug 2019 – Mar 2025

Graduate Research Assistant

- ▷ Engineering haptic actuators and wearables from the ground up to integrate new sensations into daily life & AR/VR
- ▷ Developing actuators using technologies such as soft magnetic materials, wireless power transfer & microfluidics
- ▷ Design & test custom hardware solutions including miniaturized PCBs (microcontrollers, motor drivers, wireless)
- ▷ Performing technical evaluations and psychophysical studies to characterize new devices & user experiences
- ▷ Lead focused, interdisciplinary teams to develop compelling applications and software for demoing devices
- ▷ Communicating research through papers (publishing in the best venues in my field), videos, talks, and demos

### Meta, Reality Labs Research

Haptics Research Scientist Intern

- Designed, prototyped and manufactured a bistable electromagnetic actuator with greater force, greater displacement, and faster response time than the state-of-the-art—now part of team's portfolio of actuation technologies
- ▷ Characterized electromechanical performance of the actuator with custom jigs and DAQ programming

June 2023 - Oct 2023

Redmond, WA

Chicago, IL

#### Miami University, Department of Mechanical Engineering Under/Graduate Research Assistant

Designed, fabricated and tested a variable stiffness actuator based on electrorheological fluids

> Analytically modeled actuator's performance based on soft material, fluid, and electrostatic mechanics

# Korea Advanced Institute of Science and Technology (KAIST)

Visiting Student Researcher

Daejeon, South Korea ▷ Developed COMSOL multiphysics models of a new induction heating coil geometry for thin sheet workpieces, in collaboration with the Korea Institute of Machinery and Materials (KIMM)

# Korea Advanced Institute of Science and Technology (KAIST)

Senior Capstone Research

Daejeon, South Korea > Designed applications for a tablet with novel electrostatic haptic actuators, in collaboration with the Korea Research Institute of Standards and Science (KRISS)

# **CONFERENCE PUBLICATIONS**

Conferences (e.g., CHI, UIST, VR, etc.) are generally regarded as the top-tier publications in Human Computer Interaction (20-25% acceptance rate), even when considering journals (CS is a conference-based field).

# Key Publications from PhD Thesis (Fully Refereed)

- [C.8] Power-on-Touch: Powering Actuators, Sensors, and Devices during Interaction Alex Mazursky, Aryan Gupta, Andre de la Cruz, Pedro Lopes In Proc. ACM CHI 2025 (to appear).
- [C.7] Stick&Slip: Altering Fingerpad Friction via Liquid Coatings Alex Mazursky, Jacob Serfaty, Pedro Lopes In Proc. ACM CHI 2024, with demo at IEEE Haptics Symposium.
- [C.6] ThermalGrasp: Enabling Thermal Feedback even while Grasping and Walking Alex Mazursky, Jas Brooks, Beza Desta, Pedro Lopes In Proc. IEEE VR 2024.
- [C.5] ThermalRouter: Enabling Novices to Design Thermally-Sound Devices Alex Mazursky, Borui Li, Shan-Yuan Teng, Dasha Shifrina, Joyce Passananti, Svitlana Midianko, Pedro Lopes In Proc. ACM UIST 2023.
- [C.4] MagnetIO: Passive yet Interactive Soft Haptic Patches Anywhere Alex Mazursky, Shan-Yuan Teng, Romain Nith, Pedro Lopes In Proc. ACM CHI 2021, with demos at CHI and SIGGRAPH Emerging Technologies.

# Additional Conference Publications (Fully Refereed)

- [C.3] Augmented Breathing via Thermal Feedback in the Nose Jas Brooks, Alex Mazursky, Janice Hixon, Pedro Lopes In Proc. ACM UIST 2024., with demo at UIST.
- [C.2] Physical Touch from a Robot Caregiver: Examining Factors that Shape Patient Experience Alex Mazursky, Maddie DeVoe, Sarah Sebo In Proc. IEEE RO-MAN 2022.
- [C.1] Multiphysics Modeling and Parametric Analysis of an Inductor for Heating Thin Sheet Materials Alex Mazursky, Hee-Chang Park, Sung-Hyuk Song, Jeong-Hoi Koo In Proc. ASME International Mechanical Engineering Congress & Exposition (IMECE) 2018.

Feb 2016 - May 2019 Oxford, OH

May 2018 - Aug 2018

Jun 2017 – Jul 2017

# JOURNAL PUBLICATIONS

[J.4] A Stretchable and Strain-insensitive Pressure Sensor for Accurately Digitizing the Sensation on Human and Robotic Skins

Qi Su, Yang Li, Yuzhen Chen, Shan-Yuan Teng, Jane Tunde Kelleher, Romain Nith, Ping Cheng, Nan Li, Wei Liu, Shilei Dai, Youdi Liu, **Alex Mazursky**, Jie Xu, Lihua Jin, Pedro Lopes, Qiang Zou, Sihong Wang *Science Advances 2021*.

- [J.3] Design and Experimental Evaluation of an Electrorheological Haptic Module with Embedded Sensing Alex Mazursky, Jeong-Hoi Koo, Taylor Mason, Sam-Yong Woo, Tae-Heon Yang Applied Sciences 2021, SI: Haptics: Technology and Applications. Feature Paper.
- [J.2] A Compact and Compliant Mixed Mode Electrorheological Actuator for Generating a Wide Range of Haptic Sensations

**Alex Mazursky**, Tae-Heon Yang, Jeong-Hoi Koo Smart Materials and Structures 2020.

[J.1] Design, Modeling, and Evaluation of a Slim Haptic Actuator based on Electrorheological Fluid Alex Mazursky, Jeong-Hoi Koo, Tae-Heon Yang Journal of Intelligent Material Systems and Structures 2019.

# SHORT PUBLICATIONS, WORKSHOP PAPERS & ABSTRACTS

- [A.6] Democratizing Soft Magnetic Materials Fabrication Alex Mazursky, Pedro Lopes Actuated Materials and Soft Robotics Strategies for Human-Computer Interaction Design. Workshop at CHI 2022.
- [A.5] Smell & Paste: Low-Fidelity Prototyping of Olfactory Experiences Jas Brooks, Alex Mazursky, Yudai Tanaka, Pedro Lopes Toolkits & Wearables:Developing Toolkits for Exploring Wearable Designs (TOWEAR). Workshop at CHI 2022.
- [A.4] Soft Magnetic Actuators for Wearable Tactile Feedback Alex Mazursky, Shan-Yuan Teng, Romain Nith, Pedro Lopes MRS Fall Meeting 2020. Symposium on Materials and Mechanics Challenges in Haptics.
- [A.3] Incorporating Sensing Capability in an Electrorheological Haptic Module Alex Mazursky, Tae-Heon Yang, Sam-Yong Woo, Jeong-Hoi Koo In Proc. International Conference on Adaptive Structures and Technologies (ICAST) 2019.
- [A.2] Application of Electro-Rheological Fluids for Conveying Realistic Haptic Feedback Alex Mazursky, Jeong-Hoi Koo, Tae-Heon Yang In Proc. International Conference on Adaptive Structures and Technologies (ICAST) 2018.
- [A.1] Experimental Evaluation of a Miniature Haptic Actuator based on Electrorheological Fluids Alex Mazursky, Tae-Heon Yang, Jeong-Hoi Koo In Proc. SPIE Smart Structures and Nondestructive Evaluation 2018.

# **DEMOS AT CONFERENCES**

- [D.4] Augmented Breathing, ACM UIST 2024
- [D.3] Stick&Slip, IEEE Haptics Symposium 2024
- [D.2] MagnetIO, ACM SIGGRAPH 2021
- [D.1] MagnetIO, ACM CHI 2021

# WORKSHOPS ORGANIZED

[W.2] Sensorimotor Devices: Coupling Sensing and Actuation to Augment Bodily Experience, ACM CHI 2025

[W.1] Soft Robotics and Actuated Materials for Human-Computer Interaction, ACM DIS 2023

# **HONORS & AWARDS**

Chicago Materials Research Center (MRSEC) SEED Grant, University of Chicago, 2021–2022 \$24,500 grant for "Enabling End-Users to Customize Active Materials using a CAD Assistant," with Pedro Lopes

Center for Data and Computing (CDAC) Doctoral Fellowship, University of Chicago, 2019–2020 \$2,500 grant for "Health Monitoring Based on Wearable Sweat Sensors," with Pedro Lopes and Sihong Wang

Biochips Travel Grant, University of Colorado Boulder, 2019 \$500 travel award to attend Biochips Summer School

Daniels Fellowship, University of Chicago, 2019–2020 \$8,000 award for select incoming doctoral students

NASA/OSGC Fellowship, Ohio Space Grant Consortium, 2018-2019 \$16,000 award and tuition waiver for my MS Thesis

Provost's Student Academic Achievement Award, Miami University, Fall 2017 Given to select students from the university who have "demonstrated outstanding academic excellence and have made notable contributions to their department." 10-15 awards per year across entire undergraduate student body.

NASA/OSGC Undergraduate STEM Scholarship, Ohio Space Grant Consortium, 2017–2018 \$3,500 award for "Modeling and Simulation of an Electrorheological Fluid-based Haptic Device"

Undergraduate Research Award, Miami University, Spring 2017 \$720 grant for "Design & Performance Evaluation of a Miniature Haptic Actuator based on Electrorheological Fluids"

NASA/OSGC Undergraduate STEM Scholarship, Ohio Space Grant Consortium, 2016–2017 \$3,500 award for "Application of Electrorheological Fluids for Haptic Feedback"

Redhawk Excellence Scholarship, Miami University, 2014–2018 Scholarship award based on academic achievement and rigor

President's List, MU College of Engineering and Computing, Spring 2016, 2017, 2018 Semester GPA = 4.00/4.00

Dean's List, MU College of Engineering and Computing, Fall 2014, 2015, 2016, 2017, Spring 2015 Semester GPA > 3.70/4.00

Start the Trend Challenge: First Place, MU College of Engineering and Computing, 2015 Innovation hackathon during Engineers Week with focus on contemporary issues in STEM education

# **TEACHING, MENTORING, & OUTREACH**

#### **Teaching Assistant**

Inventing, Engineering and Understanding Interactive Devices (CMSC 23220), UChicago Winter 2024, 2025 Introduction to Human Computer Interaction (CMSC 20300), UChicago Fall 2019, 2021 Dynamic Modeling of Mechanical Systems (MME 311), Miami University Fall 2016, Spring 2017

#### Mentoring During Ph.D. at UChicago

Andre de la Cruz, Undergraduate, Power-on-Touch, CHI'25 Aryan Gupta, High School, Power-on-Touch, CHI'25 Jacob Serfaty, Undergraduate, Stick&Slip, CHI'24 Borui Li, Undergraduate, *ThermalRouter*, *UIST*'23 Daria Shifrina, Undergraduate, ThermalRouter, UIST'23

Beza Desta, Undergraduate, ThermalGrasp, VR'24 Joyce Passananti, Undergraduate, ThermalRouter, UIST'23 Maddie DeVoe, Undergraduate, HRI Touch, RO-MAN'22

#### Alex Mazursky - CV

### Mentoring During M.S. at Miami University

Jake Zafar, Undergraduate, Haptics and Flexible Sensors Adam Coon, Undergraduate, Magnetorheological Fluid-based Actuators Sae-Hyun Sone, Undergraduate, Induction Heating Modeling

#### Modern Materials Technology

▷ Volunteered during the school year to co-teach a materials science course at Lindblom Math and Science Academy

Developed lecture slides, handouts, and hands-on labs and demos covering material science fundamentals

# **SERVICE & MEMBERSHIPS**

#### **Program Committee**

ACM Creativity & Cognition (C&C) Associate Chair ACM CHI Late-Breaking Work Associate Chair

#### Reviewing

I regularly review for conferences and journals (over 120 reviews since 2018). I received 10 special recognitions for outstanding reviews (formal distinction) from venues like ACM CHI, ACM UIST, IEEE WHC, and Smart Materials & Structures. I have reviewed for ACM CHI, ACM UIST, IEEE Transactions on Haptics, Smart Materials and Structures, IEEE WHC, ACM SIGGRAPH Asia, IEEE TVCG, IEEE VR, Sensors and Actuators: A. Physical, ACM/IEEE HRI, IEEE ISMAR, ACM TEI, ACM DIS, ACM C&C, IEEE RO-MAN, Eurohaptics, ISWC, ACM Augmented Humans, & ACM MUM.

#### Session Chair

"Haptics and Embodied Interaction B" session at ACM CHI

Student Volunteer	2024
IEEE Haptics Symposium IEEE VR	2024 2024
ACM/IEEE HRI	2022
Augmented Humans	2021
ACM CHI (canceled due to COVID-19)	2020
ACM UIST	2019

#### **Professional Memberships**

ACM SIGCHI, American Society of Mechanical Engineers (ASME), Tau Beta Pi

# SKILLS

Skills listed indicate significant experience gained over at least two projects/publications.

**Mechanical:** Design | Rapid prototyping & 3D printing | Mechanical testing (e.g., dynamic mechanical analysis, fixturing) | CAD (Solidworks) | Modeling (analytical) & simulation (Comsol, FEMM) | Smart & soft materials | Thermal & heat transfer | Machining (lathe & mill) | GD&T

Electrical: Microcontrollers | Printed circuit boards (KiCAD) | Signal processing | Controls | Electromagnetics

Human-Computer Interaction: Haptics | AR/VR | Perceptual experiments | Digital fabrication | Interaction design/usability

Programming: Python | C/C++ | Matlab | Unity | Applied machine learning/AI | Linux

# PROFESSIONAL DEVELOPMENT

Entrepreneurship for Science and Medicine, University of Chicago (Booth), 2024 Quarter-long course within the Chicago Booth School for Business/Polsky Center

Biochips Summer School, University of Colorado Boulder, 2019 Five-day course on digital microfluidics research led by Prof. Mirela Alistar at the ATLAS Institute

2025 2022 - 2024

2024

2019 - 2020

# Leadership in the Real World, Miami University, 2015

Semester-long course on leadership hosted by the Lockheed Martin Leadership Institute

# ADDITIONAL WORK EXPERIENCE

<ul> <li>Bruner Corporation</li> <li>Energy Engineering Intern</li> <li>Implemented energy savings solutions and improved company workflows through</li> </ul>	May 2016 – Aug 2016 <i>Columbus, OH</i> ugh scripting and automation
<ul> <li>Miami University, Institute for the Environment and Sustainability</li> <li>Undergraduate Research Assistant</li> <li>▷ Conducted policy and engineering research with focus on university efforts tow</li> </ul>	Jan 2016 – May 2016 <i>Oxford, OH</i> vard energy efficiency
HRK Engineering	May 2015 - Aug 2015

HBK Engineering Engineering Intern May 2015 – Aug 2015 *Chicago, IL* 

▷ Performed topographic land survey, settlement monitoring and construction layout for utilities industry

# **GRADUATE COURSEWORK**

**HCI/Computer Science:** Emergent Interface Technologies, Human-Robot Interaction, Printed Circuit Board Engineering, Human Computer Interaction meets Neuroscience, Machine Learning, Deep Learning for 3D Geometry, Algorithms, Discrete Math, Computer Networking

**Mechanical Engineering:** Adv. Mechanics of Materials, Engineering Analysis/Numerical Methods, Adv. Vibration, Mechanical Behavior of Materials, Biomaterials, Scientific Programming, Applied Nonlinear Dynamics

### SELECTED PRESS

<b>Stick&amp;Slip (CHI 2024)</b> "University of Chicago Computer Science Researchers To Present Ten Papers at CHI 2024," UChicago CS	2024
ThermalRouter (UIST 2023) "Can you take the heat?," Hackster.io	2023
<b>MagnetIO (CHI 2021)</b> "This could get sticky," Hackster.io "Magnet IO: New tactile actuator with voice coil," Auror Design "Ten Papers at CHI 2021 Flourish Frontiers of HCI Research at UChicago CS," UChicago CS	2021 2021 2021
Strain-Invariant Pressure Sensor (Science Advances 2021) "Stretchable pressure sensor could lead to better robotics, prosthetics," EurekAlert "Stretchable sensors could improve prosthetics and robotics," labroots	2021 2021
<b>About Alex</b> "Alex Mazursky researches fluid to help people "feel" the digital world," Miami University CEC "Two CEC students receive Provost's Student Academic Achievement Award," Miami University CEC	2018 2017